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Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Units
Drain-Source Voltage		V_{DSS}	80	V
Gate-Source Voltage		V_{GSS}	±20	V
Continuous Drain Current (Note 5) V_{GS} = 10V	T_A = +25°C T_A = +70°C	I_D	9.5 7.6	A
	T_C = +25°C T_C = +70°C	I_D	35 28	A
Maximum Continuous Body Diode Forward Current (Note 5)		I_S	2	A
Pulsed Drain Current (10µs pulse, duty cycle = 1%)		I_{DM}	80	A

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Units
Total Power Dissipation (Note 5)	T_A = +25°C	P_D	2.2	W
	T_C = +25°C		30	
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{\theta JA}$	57	°C/W
	t<10s		35	
Thermal Resistance, Junction to Case (Note 5)		$R_{\theta JC}$	4.2	
Operating and Storage Temperature Range		T_J, T_{STG}	-55 to 150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)						
Drain-Source Breakdown Voltage	BV_{DSS}	80	—	—	V	V_{GS} = 0V, I_D = 250µA
Zero Gate Voltage Drain Current	I_{DSS}	—	—	1	µA	V_{DS} = 64V, V_{GS} = 0V
Gate-Source Leakage	I_{GSS}	—	—	±100	nA	V_{GS} = ±20V, V_{DS} = 0V
ON CHARACTERISTICS (Note 6)						
Gate Threshold Voltage	$V_{GS(th)}$	1	1.5	3	V	V_{DS} = V_{GS}, I_D = 250µA
Static Drain-Source On-Resistance	$R_{DS(ON)}$	—	13	16	mΩ	V_{GS} = 10V, I_D = 12A
		—	14	22		V_{GS} = 6V, I_D = 6A
Diode Forward Voltage	V_{SD}	—	0.9	1.2	V	V_{GS} = 0V, I_S = 12A
DYNAMIC CHARACTERISTICS (Note 7)						
Input Capacitance	C_{iss}	—	1949	—	pF	V_{DS} = 40V, V_{GS} = 0V, f = 1MHz
Output Capacitance	C_{oss}	—	177	—		
Reverse Transfer Capacitance	C_{rss}	—	10	—		
Gate resistance	R_g	—	0.7	—	Ω	V_{DS} = 0V, V_{GS} = 0V, f = 1MHz
Total Gate Charge (V_{GS} = 4.5V)	Q_g	—	15	—	nC	V_{DS} = 40V, I_D = 12A
Total Gate Charge (V_{GS} = 10V)	Q_g	—	34	—		
Gate-Source Charge	Q_{gs}	—	6	—		
Gate-Drain Charge	Q_{gd}	—	4.5	—		
Turn-On Delay Time	$t_{D(on)}$	—	4.9	—	nS	V_{DD} = 40V, V_{GS} = 10V, I_D = 12A, R_G = 1.6Ω,
Turn-On Rise Time	t_r	—	3.8	—		
Turn-Off Delay Time	$t_{D(off)}$	—	16.5	—		
Turn-Off Fall Time	t_f	—	3.5	—		
Body Diode Reverse Recovery Time	t_{rr}	—	30.2	—	nS	I_F = 12A, di/dt = 100A/µs
Body Diode Reverse Recovery Charge	Q_{rr}	—	34.6	—	nC	

Notes:
5. $R_{\theta JA}$ is determined with the device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate. $R_{\theta JC}$ is guaranteed by design while $R_{\theta JA}$ is determined by the user's board design.
6. Short duration pulse test used to minimize self-heating effect.
7. Guaranteed by design. Not subject to product testing.

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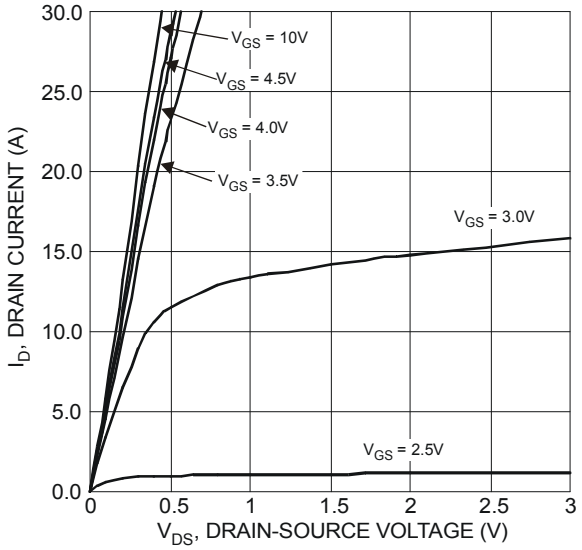

Figure 1 Typical Output Characteristics

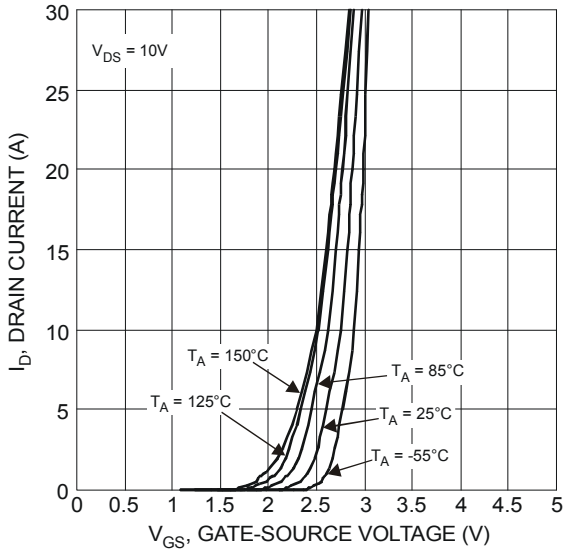

Figure 2 Typical Transfer Characteristics

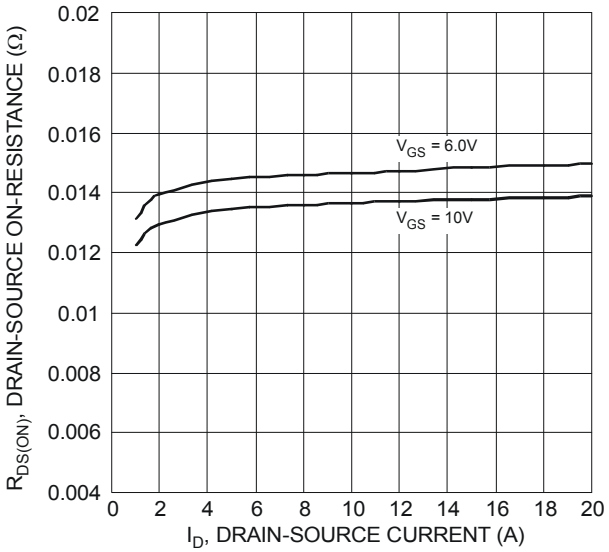

Figure 3 Typical On-Resistance vs. Drain Current and Gate Voltage

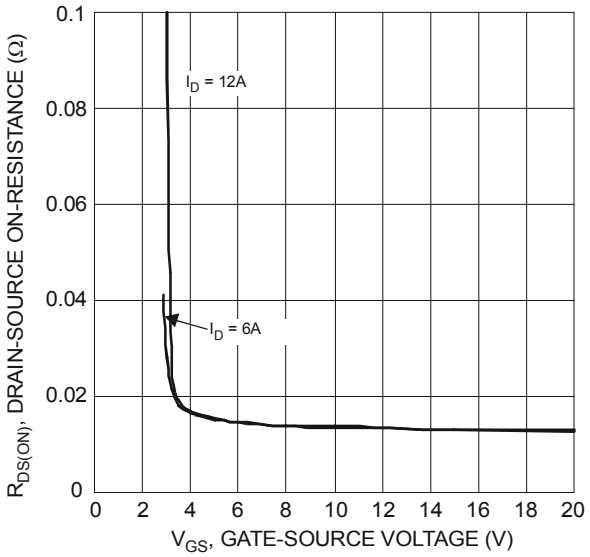

Figure 4 Typical Transfer Characteristics

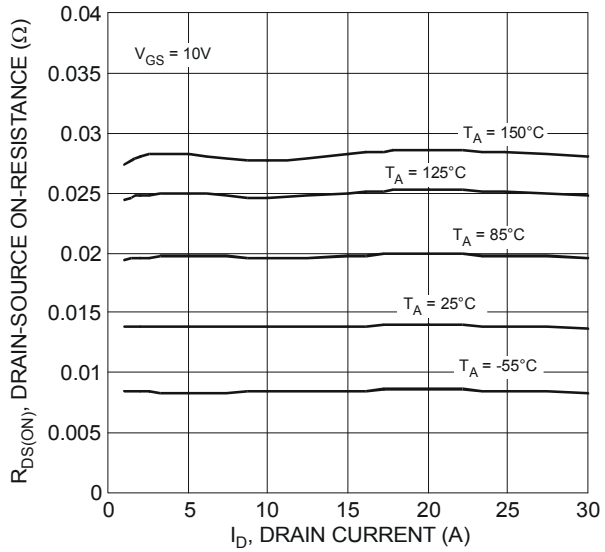

Figure 5 Typical On-Resistance vs. Drain Current and Temperature

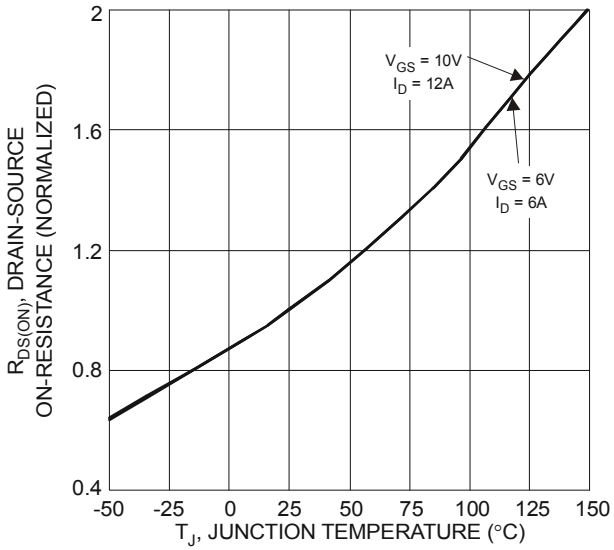

Figure 6 On-Resistance Variation with Temperature

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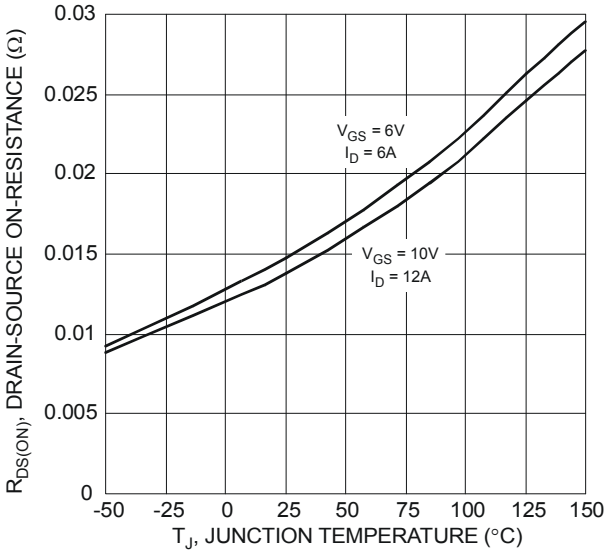

Figure 7 On-Resistance Variation with Temperature

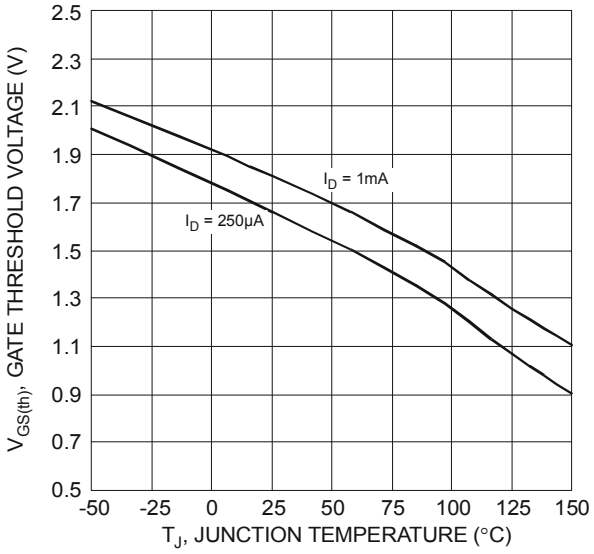

Figure 8 Gate Threshold Variation vs. Ambient Temperature

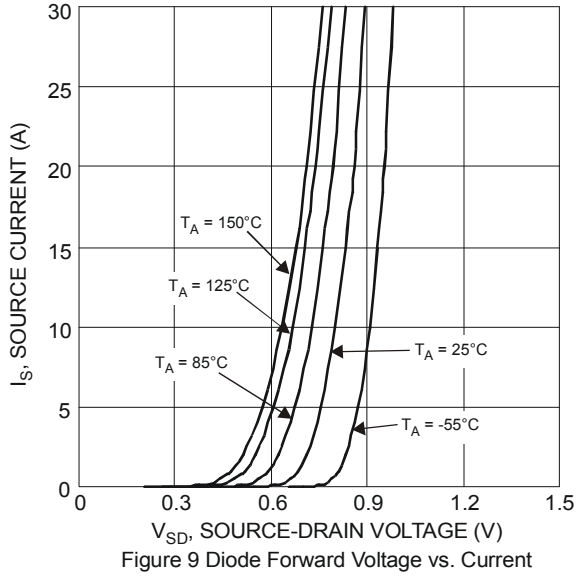

Figure 9 Diode Forward Voltage vs. Current

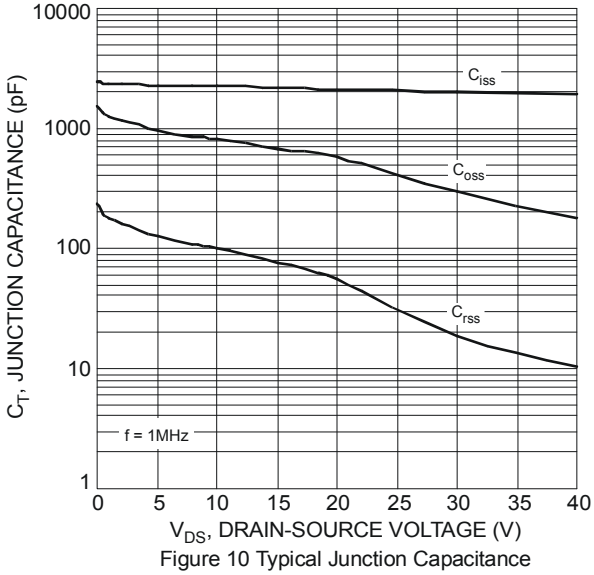

Figure 10 Typical Junction Capacitance

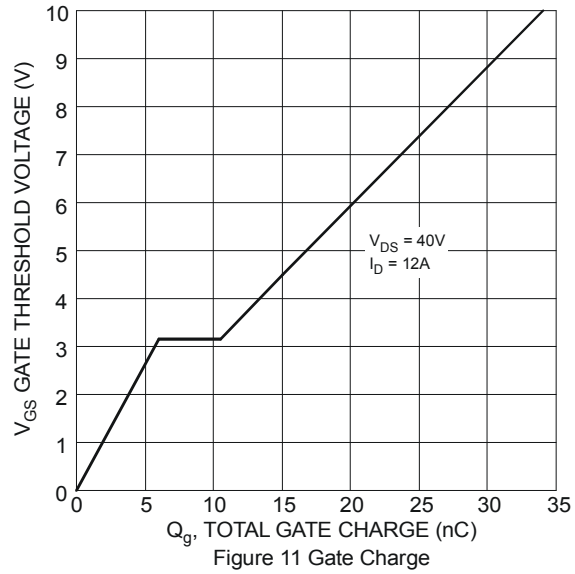

Figure 11 Gate Charge

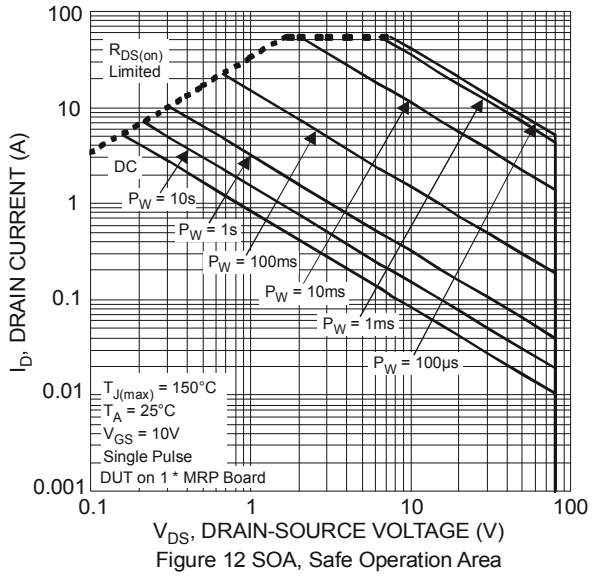

Figure 12 SOA, Safe Operation Area

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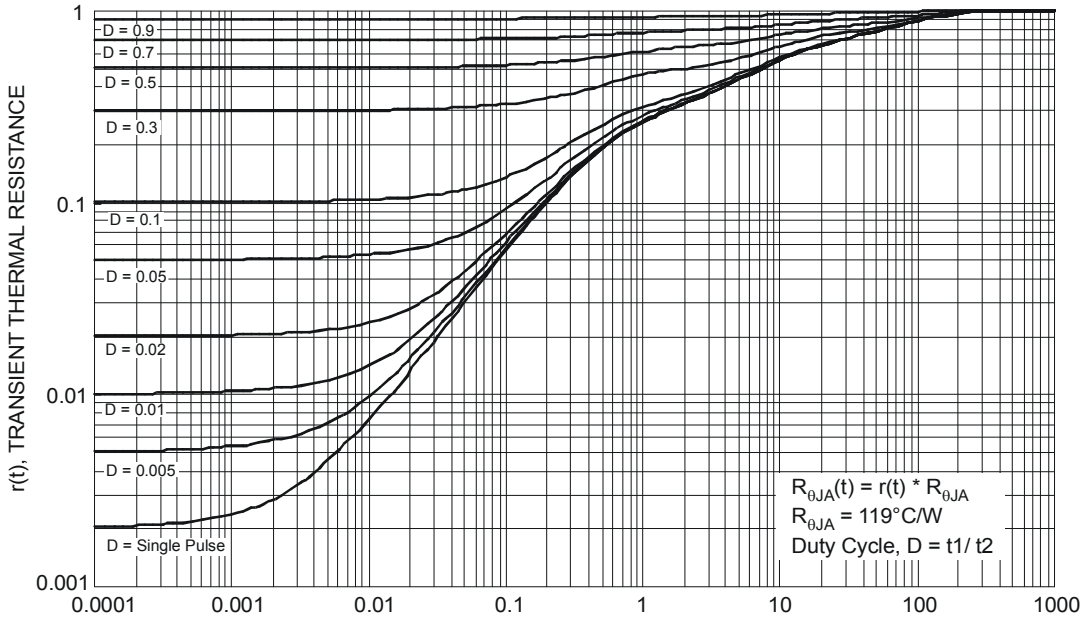
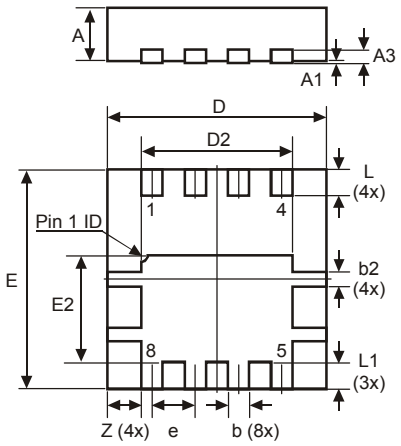


Figure 13 Transient Thermal Resistance

Package Outline Dimensions

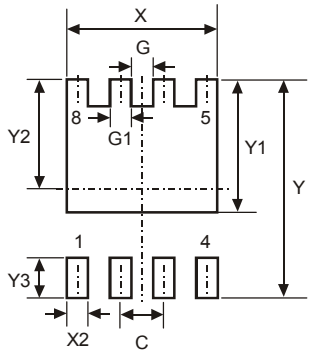
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



POWERDI®3333-8			
Dim	Min	Max	Typ
D	3.25	3.35	3.30
E	3.25	3.35	3.30
D2	2.22	2.32	2.27
E2	1.56	1.66	1.61
A	0.75	0.85	0.80
A1	0	0.05	0.02
A3	–	–	0.203
b	0.27	0.37	0.32
b2	–	–	0.20
L	0.35	0.45	0.40
L1	–	–	0.39
e	–	–	0.65
Z	–	–	0.515
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for latest version.



Dimensions	Value (in mm)
C	0.650
G	0.230
G1	0.420
Y	3.700
Y1	2.250
Y2	1.850
Y3	0.700
X	2.370
X2	0.420

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